

**Amendments to the Specification**

Add the following numbered paragraphs:

[0045.1] FIG. 14 is a side view of embodiment of the invention of FIG.13 of a low profile multi-IC chip package incorporating a package connector of the invention.

[0074.1] Illustrated in drawing FIG. 14 is the multi-IC package 130 having panels of the cage 132 surrounding a plurality of vertical primary packages 14, which have outer leads 16 contacting conductive pads 34 or elongate leads of the host circuit board 30, attached by adhesive 136 to the circuit board 30. Since the multi-chip package 130 has three panels forming the cage 132 surrounding the vertical primary packages 14, the ends of the cage 132 are open.